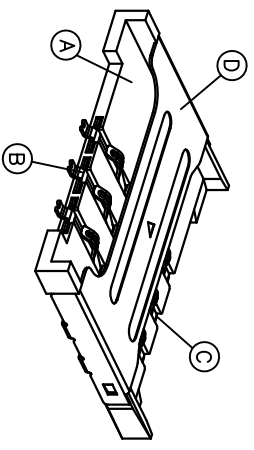
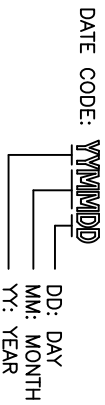


SECTION: A-A
SCALE: 1/1

NOTES:

1. ELECTRICAL PERFORMANCES:
 - 1.1 CURRENT RATING: 0.50 A MAX.
 - 1.2 CONTACT RESISTANCE: 50 mΩ MAX.
 - 1.3 INSULATION RESISTANCE: 100 MΩ MIN.
 - 1.4 DIELECTRIC WITHS TANDING VOLTAGE: 250V AC FOR 1 MINUTE.
2. MECHANICAL PERFORMANCES:
 - 2.1 CONTACT NORMAL FORCE: 0.30N MIN. AT DEFLECTION.
 - 2.2 MECHANICAL OPERATION: 5000 CYCLES.
 - 2.3 OPERATING TEMPERATURE: -40°C TO 85°C
3. HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT: ©
4. HALOGEN FREE PRODUCT IDENTIFICATION LOGO ON PACKING: ©
5. FOR LEAD-FREE PRODUCT.
6. SOLDERING HEAT RESISTANCE: 260°C 10 SEC.
7. PRINTED DATE CODE "YMMDD" ON TOP OF CONNECTOR.

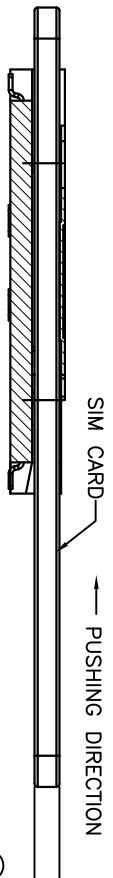
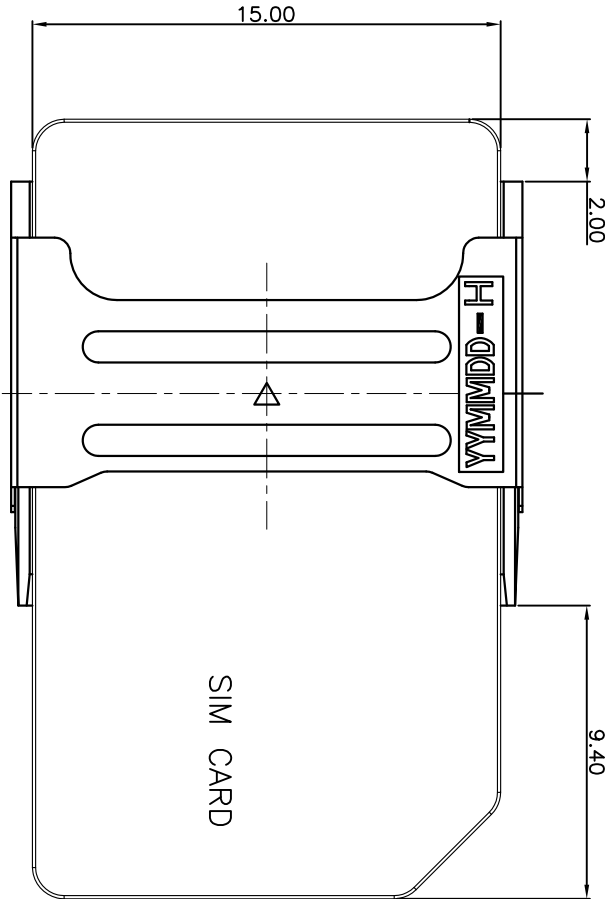
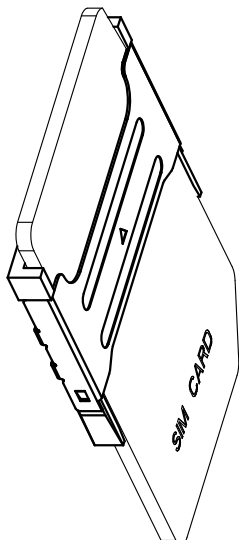


REV.	ECN NO.	OR DESCRIPTION	REVISED	DATE
C	ECN NO: S080130	BOYE QI	2008.02.01	
D	ECN NO: T080204	LII	2008.12.10	
E	ECN NO: 100411	Ryan	2010.05.17	

D	COVER	1	STAINLESS STEEL 0.12t	GOLD FLASH ON SOLDER AREA OVER 500" IN.
C	CONTACT-2	3	PHOSPHOR BRONZE 0.12t	GOLD FLASH ON CONTACT AREA AND SOLDER AREA ALL OVER 500" IN.
B	CONTACT-1	3		
A	BODY	1	HIGH TEMP THERMOPLASTIC	BLACK
UNLESS OTHERWISE SPECIFIED TOLERANCES		MATERIAL		PLATING & COLOR
DECIMALS:		ANGLES:		
X	:±0.5	X	:±2°	
X.X	:±0.3	X.X	:±1°	
X.XX	:±0.2			
TITLE		SIM CARD CONN.		
DWN Tom		PART NO. 2SM3003-002111		
CHKD Lussen		SCALE: 4:1 UNIT: mm		
APVD Max		SIZE: A3 SHEET: 1 OF 2 REV: E		

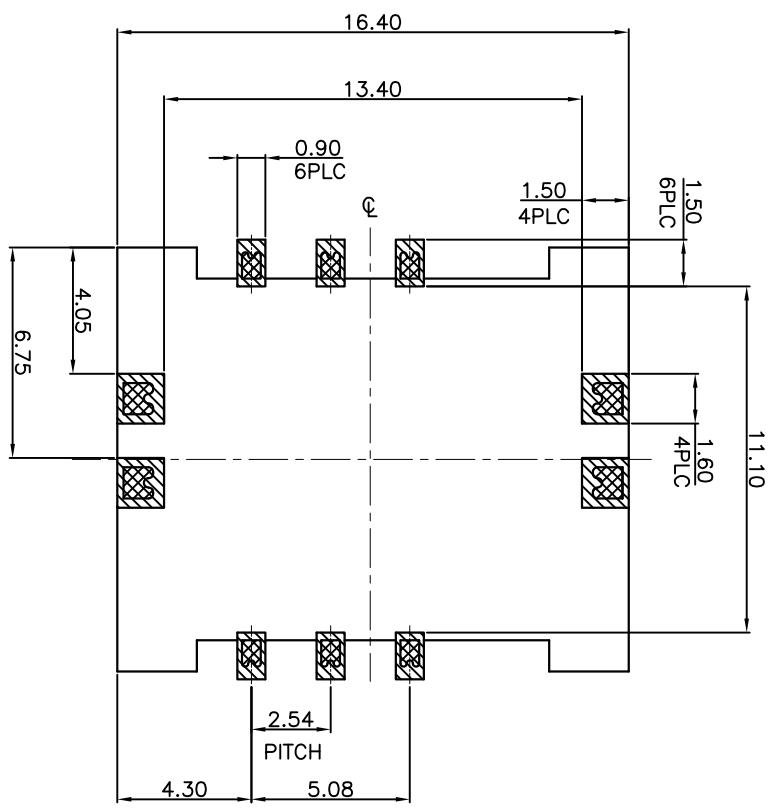
Singatron Enterprise Co., Ltd.
信登企業股份有限公司

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USE GUIDE

(0.80)



RECOMMENDED P.C.B LAYOUT(TOP VIEW)
TOLERANCE ±0.05mm

REV.	ECN NO.	OR DESCRIPTION	REVISED	DATE
C	ECN NO: S080130	BOYE.QI	2008.02.01	
D	ECN NO: T080204	LII	2008.12.10	
E	ECN NO:100411	Ryan	2010.05.17	

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS: ANGLES:

X: ±0.5 X: ±2°
X.X: ±0.3 X.X: ±1'
X.XX: ±0.2

Singatron Enterprise Co., Ltd.
信譽企業股份有限公司

TITLE: SIM CARD CONN.

DWN Tom PART NO. 2SM3003-002111

CHKD Lussen SCALE: 4:1 UNIT: mm

APVD Max SIZE: A3 SHEET: 2 OF 2 REV: E

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